



Click [here](#) for the 3D model.

Dimensions

L	1.6mm +/-0.2mm
W	3.2mm +/-0.2mm
T	0.8mm +/-0.10mm
P	0.8mm +/-0.10mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	Array Auto COG Flex
Style	SMD Array
Description	SMD, MLCC, Array, Flex Termination, Automotive Grade
Features	Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	18 mg
Notes	Last Time Buy Date (LTB): May 30th, 2024.
Chip Size	0612
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms